

产品规格书

SPECIFICATION

CUSTOMER 客户： _____

PRODUCT 产品： _____ SAW FILTER _____

MODEL NO 型号： _____ HDBF14015A63 SF6-3 _____

PREPARED 编制： 汤康君 CHECKED 审核： _____

APPROVED 批准： _____ D A T E 日期： _____ 2010-11-11 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

1. SCOPE

This specification shall cover the characteristics of SAW filter with HDBF14015A63 used for the page system.

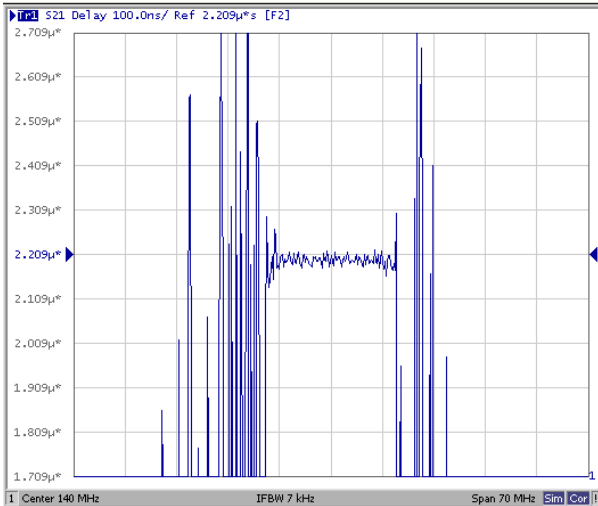
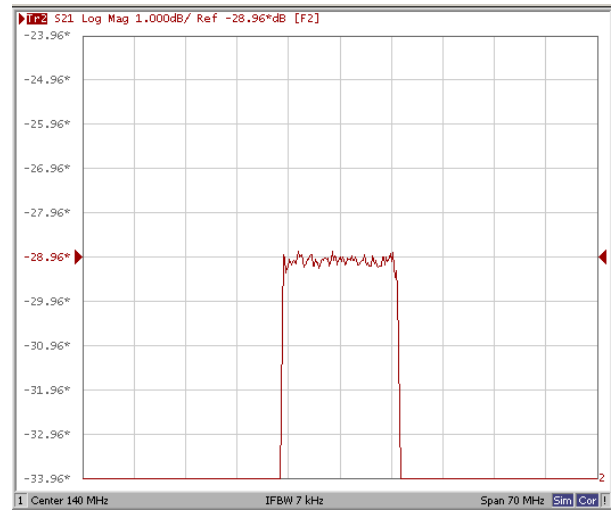
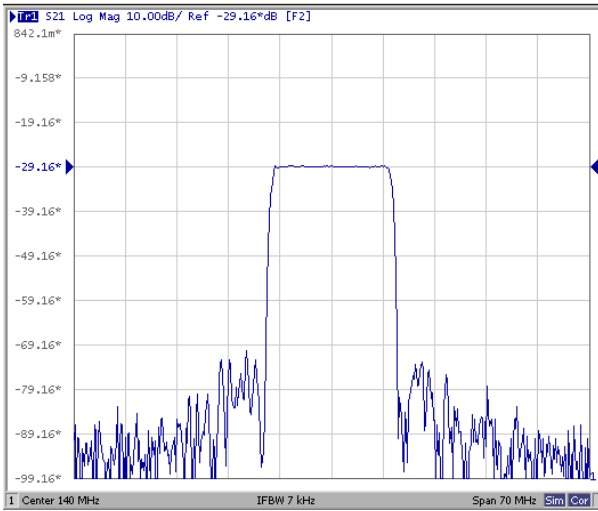
2. ELECTRICAL SPECIFICATION

Maximum Input Power	+10dBm
DC voltage	10V
Storage Temperature Range	-45°C to +85°C
Operation Temperature Range	-40°C to +85°C

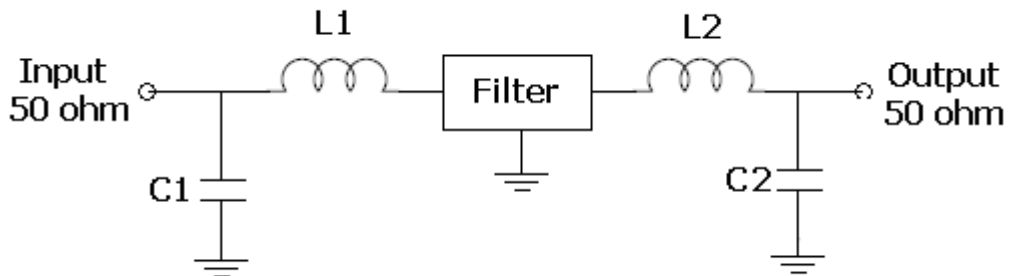
2.2 Electronic Characteristics

Parameter	Min.	Typical.	Max.	Unit
Center Frequency	139.8	140	140.2	MHz
Insertion loss		29	30	dB
Passband ripple(-1 dB)		0.9	1	dB
-1dB Bandwidth	15.5	15.7		MHz
-3dB Bandwidth	15.8	16		MHz
-40dB Bandwidth		17.8	19	MHz
Rejection:				dB
25MHz—120MHz	50	55		
120.5MHz—128.5MHz	40	45		
151.5MHz—157.5MHz	40	45		
158MHz—300MHz	50	55		
Absolute Delay		2.2	3	usec
Group Delay Variation		100	150	nsec
Temperature Coefficient		-87		ppm/°C
Package Size	SF6-3			

2.3 Typical Frequency Response



3. TEST CIRCUIT

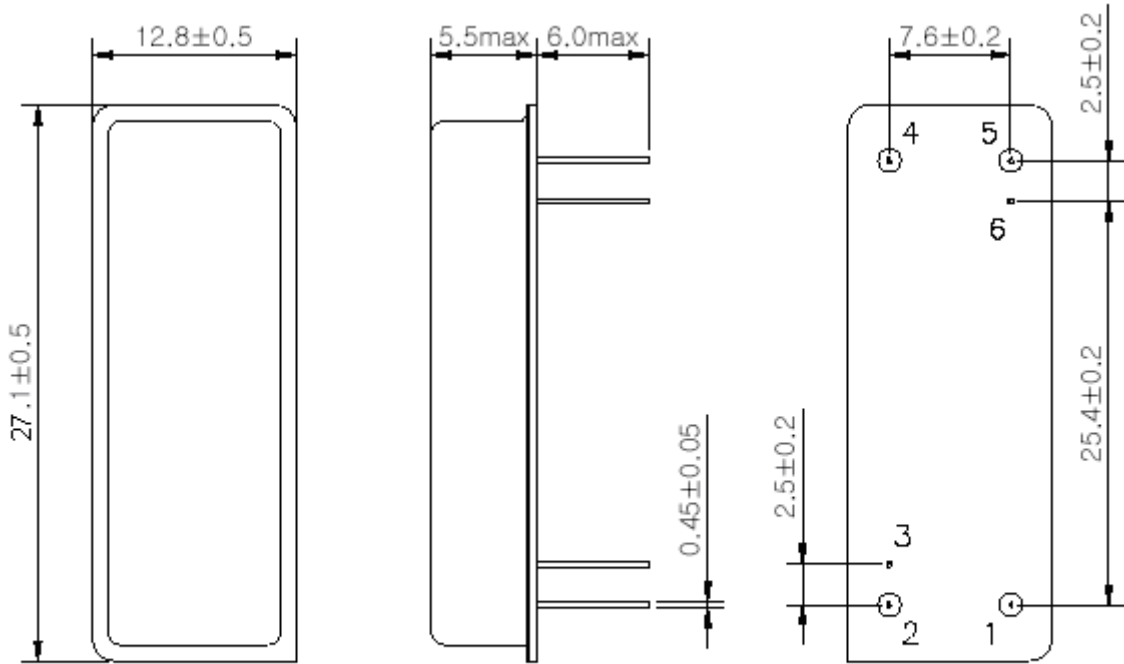


Input : L1 = 27 nH , C1 = 27 pF

Output : L2 = 15 nH , C2 = 9 nH

* Component values may change depending on board layout.

4.DIMENSION



Pin Configuration	
1	Input
5	Output
2, 4	Ground
Other	Case ground

5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C ±10°C for

10±1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

5-5 Solderability

Subject the device terminals into the solder bath at 245°C ±5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.